

1. Scope :

This specification applies to N/P/N silicon zener double diodes chips,
Device NO. SD-00866GVA

2. Structure :

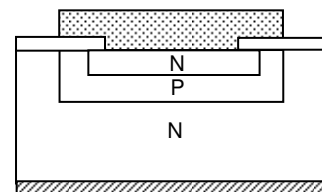
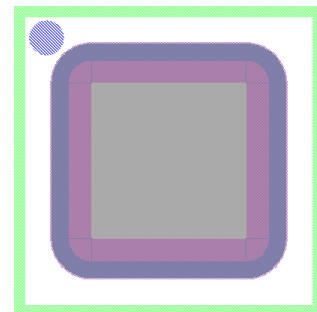
- 2-1. Planar type : N/P/N.
- 2-2. Electrodes :
Top side : Gold pad.
Back side : SnAu Alloy.

3. Size :

- 3-1. ^{※1}Chip size : 8.5 mils x 8.5 mils (0.215 mm x 0.215 mm).
- 3-2. Chip thickness : 4.0 ± 1.0 mils (0.100 ± 0.0254 mm).
- 3-3. ^{※2}Bonding pad : 5.9 mils x 5.9 mils (0.150 mm x 0.150 mm) .
- 3-4. Pattern drawing : Refer to the attached drawing.
^{※1}Including scribing line. The chip size is about $(0.190 \pm 0.015)^2 \text{mm}^2$ after dicing.
^{※2}The bonding pad dimension is $(0.150 \pm 0.005)^2 \text{mm}^2$.

4. Electrical characteristics (Ta = 25 °C) _one Zener

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Leakage Current	Idf	V=4V Ee=0mW/cm ²			100	nA
	Idr	V=4V Ee=0mW/cm ²			100	
Zener Voltage	Vz(forward)	Izf=5mA Ee=0mW/cm ²	5.5		7.0	V
	Vz(reverse)	Izr=5mA Ee=0mW/cm ²	5.3		6.8	

**5. Annotation :**

- 5-1. Parallel with one LED
- 5-2. Single pad (one wire bonding applied only)
- 5-3. Double direction Zener diode protection

Equivalent Circuit

